

WAFER GRINDING APPARATUS

Abstract

A wafer grinding apparatus includes a wafer-transporting device for transporting a wafer, a first nozzle, and a second nozzle. The wafer-transporting device includes at least a suction pad having a first surface and a second surface that is flexible for sucking the wafer, and a transporting mechanism connected to the first surface of the suction pad for transporting the wafer. The first nozzle is used for ejecting a first liquid to the first surface of the suction pad for cleaning the first surface, and the second nozzle is used for ejecting a second liquid to the second surface of the suction pad and the wafer for cleaning the second surface and the wafer.